

TLVR Series Molding Power Inductors Size 100510



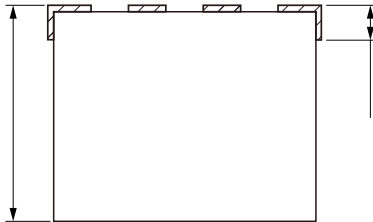
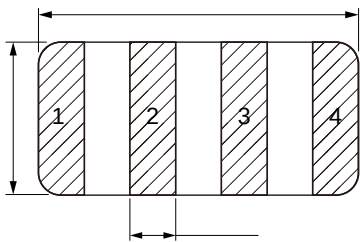
FEATURES

- Higher current carrying Capacity, lower DCR, and more efficiency.
- Operating temperature: -55 to +125 °C(Including self - temperature rise).
- Quantity: 400PCS

APPLICATION

- AI Servers, Data Centers, GPU/AI Accelerators.
- Desktop Motherboards, CPU/GPU Power Delivery.
- Multi-phase VRM, High-current DC-DC Converters.
- Networking Equipment, Communication Infrastructure.

Dimensions: [mm]



Schematic:

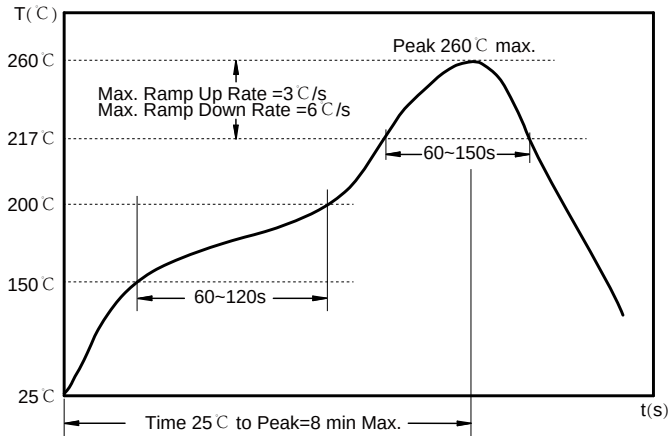


Electrical Properties:

Part No	Inductance (μH)	Min. (nH)	Resistance (mΩ)	Resistance (mΩ)	Rise Current	Saturation Current	Hi-Pot Min.	Min.

All test data is referenced to 25 °C ambient.
Saturation Current will cause L0 to drop approximately 30%.
Temperature Rise Current: The actual value of DC current when the temperature rise is ΔT=40 °C.
FLL: tested @100 kHz, 1.0 Vrms, Isat, applied for +25 °C.
Hi-Pot: as pass / fail judgement, tested @ 2s,2mA, between 2 windings.

Soldering Reflow:



Preheat condition: 150 ~200 °C/ 60~120 sec.

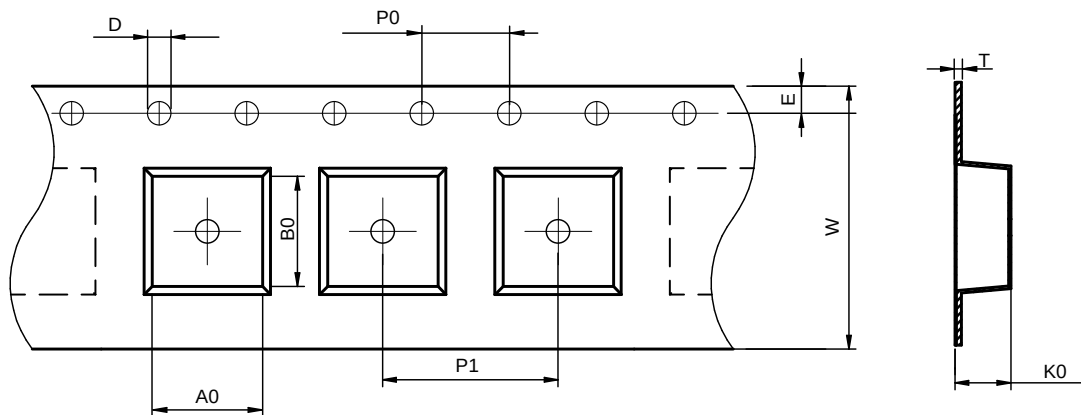
Allowed time above 217 °C: 60~150 sec.

Max temperature: 260 °C.

Time within 5 °C of actual Peak Temperature: 30 max. sec.

Packaging Information:

Tape Dimension:



A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)

Product Marking:

Marking	Printing Inductance)
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